

APPARATUS FOR EDGE POLISHING UNIFORMITY CONTROL

ABSTRACT OF THE DISCLOSURE

An invention is provided for a platen for use in a CMP system. The platen

- 5 includes an inner set of pressure sub regions capable of providing pressure to a polishing pad disposed above the platen. Each of the inner pressure sub regions is disposed below a wafer and within a circumference of the wafer. In addition, the platen includes an outer set of pressure sub regions capable of providing pressure to a polishing pad. Each of the outer set of pressure sub regions is disposed below the wafer and outside the
- 10 circumference of the wafer. In this manner, the outer set of pressure sub regions is capable of shaping the polishing pad to achieve a particular removal rate.